

## Declaration of Compliance

We declare that our green products for customer comply with all RoHS regulations. We are willing to provide all necessary documentation or information to prove our compliance with the RoHS regulations. It is our responsibility to proactively inform our customer if we identify that there is a potential risk of breaching the RoHS regulations in our product.

### 1. Product Information

**Product Model P/N: AS7312-54XS**

**Product Description: 25 GbE Data Center Switch**

### 2. Classification

Edge-Core Networks approve and follow the exclude article of EU RoHS for components and product.

- ☒ a. Full compliance with RoHS 2.0(2011/65/EU) requirements (6 items forbid materials)  
Pb, Hg, Cr6+, PBB, PBDE < 1000 ppm, Cd < 100 ppm
- ☐ b. Full compliance with RoHS 2.0(2011/65/EU) +PFOS(2006/122/EC) requirements (7 items forbid materials)  
Pb, Hg, Cr6+, PBB, PBDE < 1000 ppm, Cd < 100 ppm, PFOS<1000 ppm
- ☐ c. Partial compliance with RoHS 2.0(2011/65/EU) requirements (except Pb) (5/6)  
Hg, Cr6+, PBB, PBDE < 1000 ppm, Cd < 100 ppm
- ☒ d. Full compliance with China RoHS requirements (6 items forbid materials)  
Pb, Hg, Cr6+, PBB, PBDE < 1000 ppm, Cd < 100 ppm
- ☒ e. Full compliance with REACH(EC 1907/2006)requirements
- ☒ f. Full compliance with Taiwan RoHS-CNS 15663 requirements

### RoHS 6/6 :

Meet RoHS 2(2011/65/EU) and use RoHS Exemption as below :

6a : Lead as an alloying element in steel for machining purposes and in galvanised steel containing up to 0,35 % lead by weight .

6b : Lead as an alloying element in aluminium containing up to 0,4 % lead by weight .

6c : Copper alloy containing up to 4 % lead by weight .

7a : Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead) .

7c-l : Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound.

**China RoHS:**

产品内含危害物质揭露表 Products contain hazardous substances exposing table						
零部件名称 Component Name	危害物质项目 Hazardous Substances Project					
	铅 (Pb)	镉 (Cd)	汞 (Hg)	六价铬 (Cr6+)	多溴联苯 (PBB)	多溴二苯乙醚 (PBDE)
固态硬盘 SSD Module	X	○	○	○	○	○
动态随机存取内存模块 SDRAM Module	X	○	○	○	○	○
电压转换集成电路 Regulator	X	○	○	○	○	○
风扇 Fan	X	○	○	○	○	○
螺丝 Screw	X	○	○	○	○	○
螺丝帽 Nut	X	○	○	○	○	○
电源供应器 Power supply	X	○	○	○	○	○
电阻 Resistor	X	○	○	○	○	○
本表格依据 SJ/T : 11364-2014 的规定编制。						
○ : 表示此部件使用的所有同类材料中此种有毒或有害物质的含量均低于 GB/T 26572-2011 规定的限制要求。 ○ : indicates the toxic or hazardous substance content of the part (at the homogenous material level) is lower than the threshold defined by Requirements for Concentration Limits for Toxic or hazardous Substances in Electronic Information Products(GB/T 26572-2011) issued by Chinese Ministry of Information Industry ("Not Contained" toxic or hazardous substances).						
X:表示此部件使用的至少一种同类材料中,此种有毒或有害物质的含量高于 GB/T 26572-2011 规定的限制要求。 X: indicates the toxic or hazardous substance content of the part (at the homogenous material level) is over the threshold defined by standard of GB/T 26572-2011( "Contained" toxic or hazardous substances). Suppliers can explain the technical cause of "X" according to actual situation.						

**REACH :**

Meet REACH 181 SVHCs (Directive EC 1907/2006) and REACH SVHC material list follow ECHA web announce.

<http://echa.europa.eu/web/guest/candidate-list-table>

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Signature: 

Date: 3/27/2018